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<u> </u>	1			
	5719	((pressure\$4 near6 (test\$4 detect\$4 inspect\$4 measur\$4 sens\$4 gauge indicat\$4 estimat\$4evaluat\$4 calculate\$4determin\$4 identif\$4 transducer cell monitor\$4 comput44).clm.) and (gas fluid liquid steam air water).clm.) and heat\$4.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:08
-	244	(((pressure\$4 near6 (test\$4 detect\$4 inspect\$4 measur\$4 sens\$4 gauge indicat\$4 estimat\$4evaluat\$4 calculate\$4determin\$4 identif\$4 transducer cell monitor\$4 comput44).clm.) and (gas fluid liquid steam air water).clm.) and heat\$4.clm.) and substrate.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:08
-	88	(pressure\$4 near6 (test\$4 detect\$4 inspect\$4 measur\$4 sens\$4 gauge indicat\$4 estimat\$4evaluat\$4 calculate\$4determin\$4 identif\$4 transducer cell monitor\$4 comput44).clm.) and (gas fluid liquid steam air water) and heat\$5 near3 (membrane deformable elastic\$4 resilien\$5 diaphragm).clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:11
-	14	((pressure\$4 near6 (test\$4 detect\$4 inspect\$4 measur\$4 sens\$4 gauge indicat\$4 estimat\$4evaluat\$4 calculate\$4determin\$4 identif\$4 transducer cell monitor\$4 comput44).clm.) and (gas fluid liquid steam air water) and heat\$5 near3 (membrane deformable elastic\$4 resilien\$5 diaphragm).clm.) and substrate.clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/09/21 13:11
-	2	("5511428").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	2647	"5" and stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	0	(("5511428").PN.) and stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:06
-	186187	(thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:37
-	92332	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)) and (gap groove dip recess\$4 space opening hole crack)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/26 10:29
-	68	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge)) and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same stiction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:30
-	7769	(thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:29
-	2750814	"8" and (gap groove dip recess\$4 space opening hole crack) .	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:30

-	3643	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:35
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack)	DERWENT;	
		///Ab armad b and) = and 2 /ann aft A	IBM_TDB	0000/00/00 40:04
-	0	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:31
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack)) and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same	DERWENT;	
		and (water54 layer54 substrate54 disk54 lilm54) same stiction	IBM_TDB	
	1	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:31
-	'	detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	2003/09/20 10.31
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	
		and stiction	IBM TDB	
l _	0	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:34
	ı	detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB:	2003/03/20 10:54
1		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) near3	IBM_TDB	
	1	stiction	10700	
_	1964	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:35
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB:	_,
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4	IBM_TDB	
		adhere\$4 stick\$4) near3 stiction	_	
-	2823	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:35
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
	1	indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4	DERWENT;	
		adhere\$4 stick\$4) near3 stiction	IBM_TDB	
-	0	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:36
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction	DERWENT;	
İ	103	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:46
	103	adhere\$4 stick\$4) near3 stiction	US-PGPUB;	2000/00/20 10.40
İ		adhered sticker heard stiction	EPO; JPO;	
			DERWENT:	
			IBM TDB	
_	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:37
		adhere\$4 stick\$4) near3 stiction) and(thermal heat) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
	- 0	monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	•
		estimat\$4 transducer gauge)	IBM_TDB	
-	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:43
1.		adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	
		estimat\$4 transducer gauge)	IBM_TDB	2002/00/26 40:40
-	2	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:42
		adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	US-PGPUB; EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	
		estimat\$4 transducer gauge) same gas	IBM TDB	
_	36	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:43
		adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	
	1	estimat\$4 transducer gauge)	IBM_TDB	
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·	11	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:48
		adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	[
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT:	
İ		estimat\$4 transducer gauge) same gas	IBM TDB	
1 -	1708	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:48
		adhere\$4 stick\$4) near3 (stiction friction)	US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM TDB	
_	15	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 11:57
		adhere\$4 stick\$4) near3 (stiction friction)) and (thermal	US-PGPUB;	
		heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4	EPO; JPO;	
		determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4	DERWENT	
		evaluat\$4 estimat\$4 transducer gauge) same gas	IBM_TDB	